Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material:**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref: DCA**

**APPROVED BY: DK DIE SIZE .019 X .019” DATE: 10/18/21**

**MFG: ALLEGRO/SPRAGUE THICKNESS .008” P/N: 2N4401**

**DG 10.1.2**

#### Rev B, 7/19/02